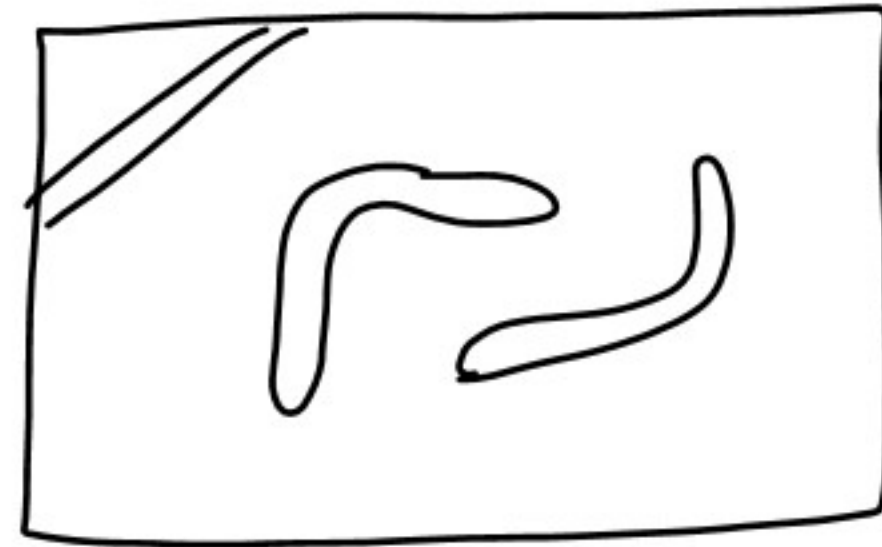
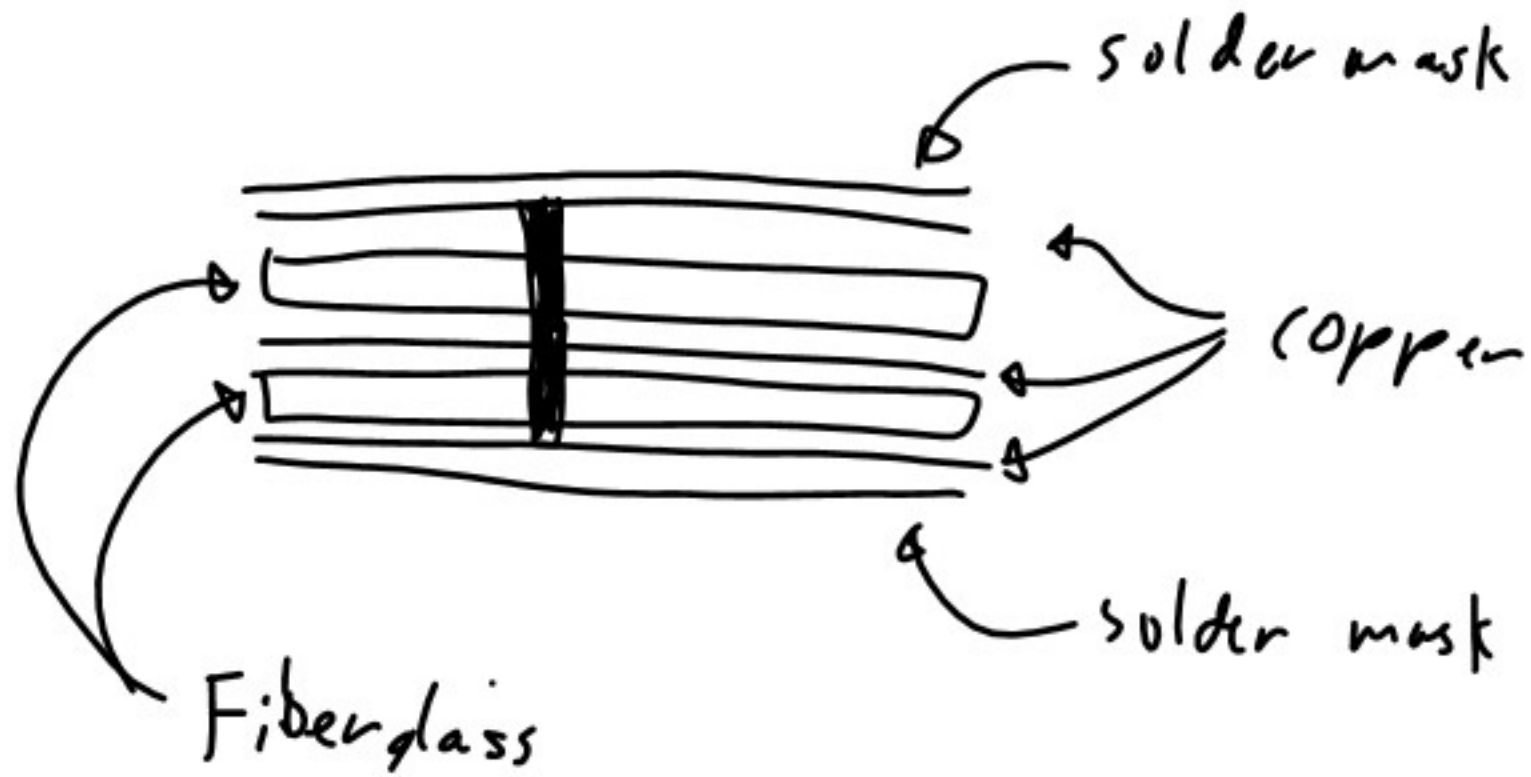


Circuit Board Manufacturing

KiCAD



Etching

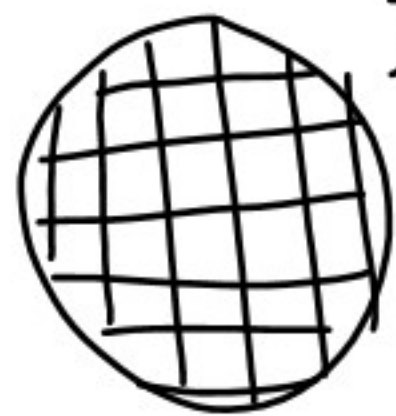
Chip Fabrication

5 nm process

2x dia DNA

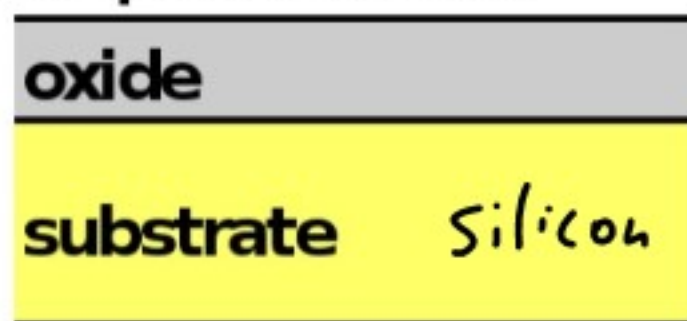
hair dia 80,000 to 100,000 nm

Silicon Wafer

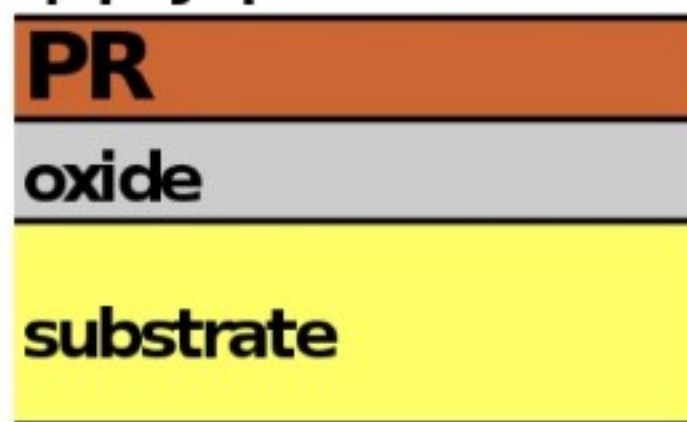


300 mm dia

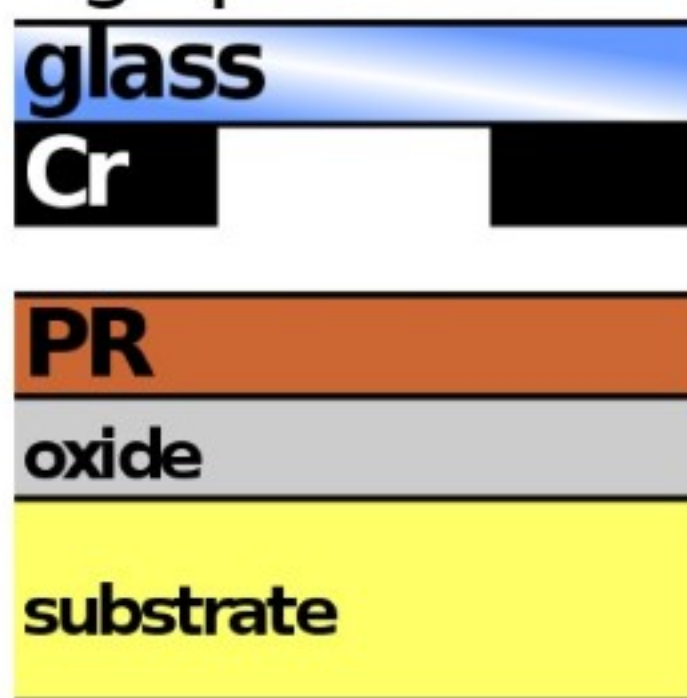
a. Prepare wafer



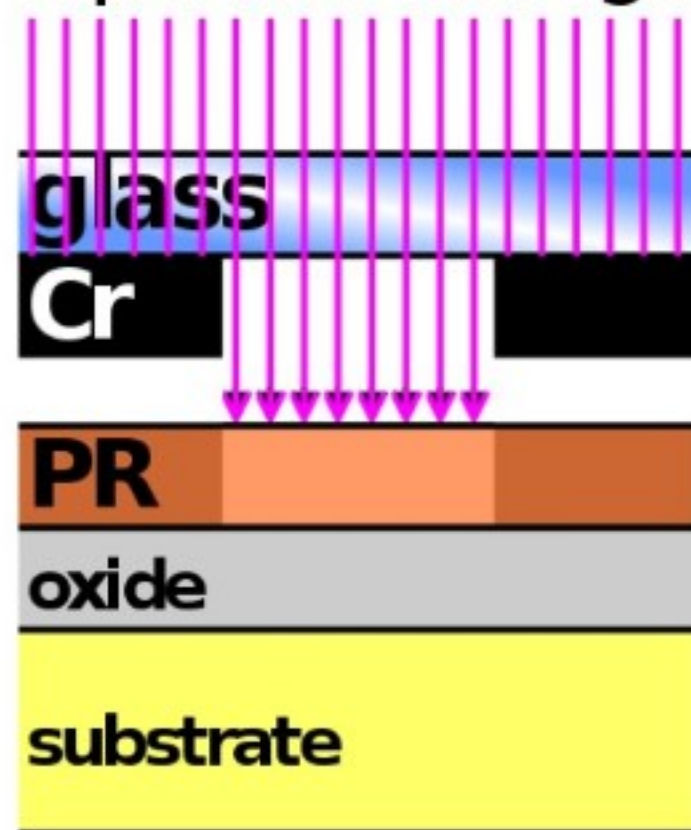
b. Apply photoresist



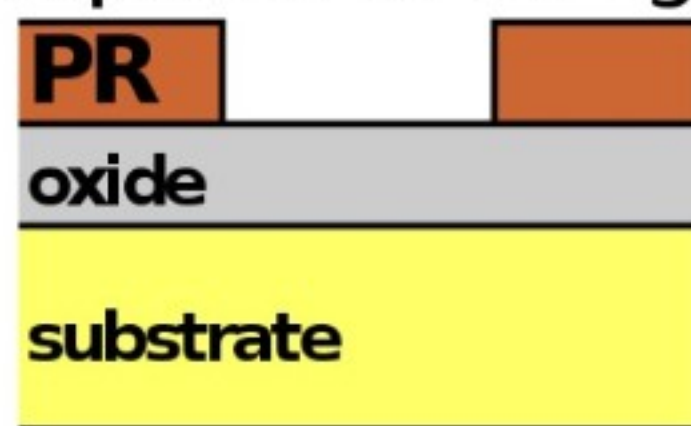
c. Align photomask



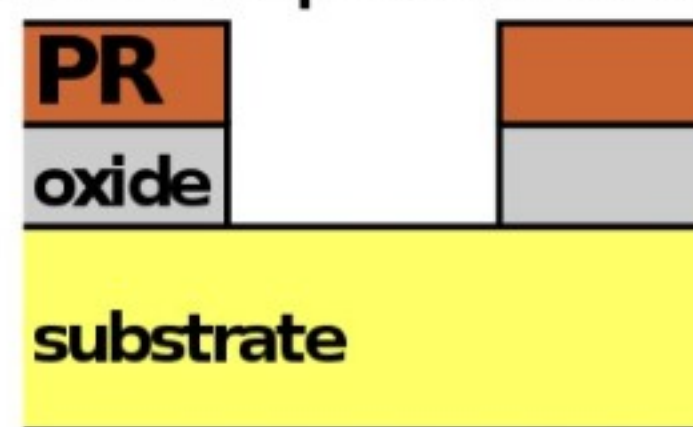
d. Expose to UV light



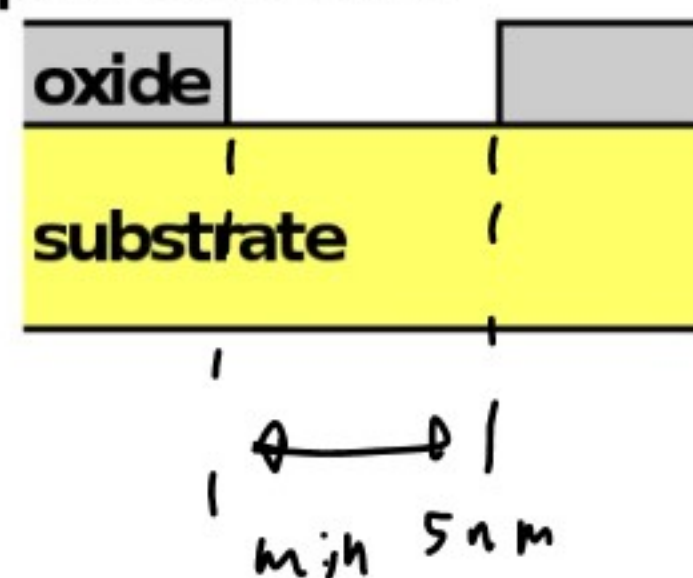
e. Develop and remove photoresist exposed to UV light



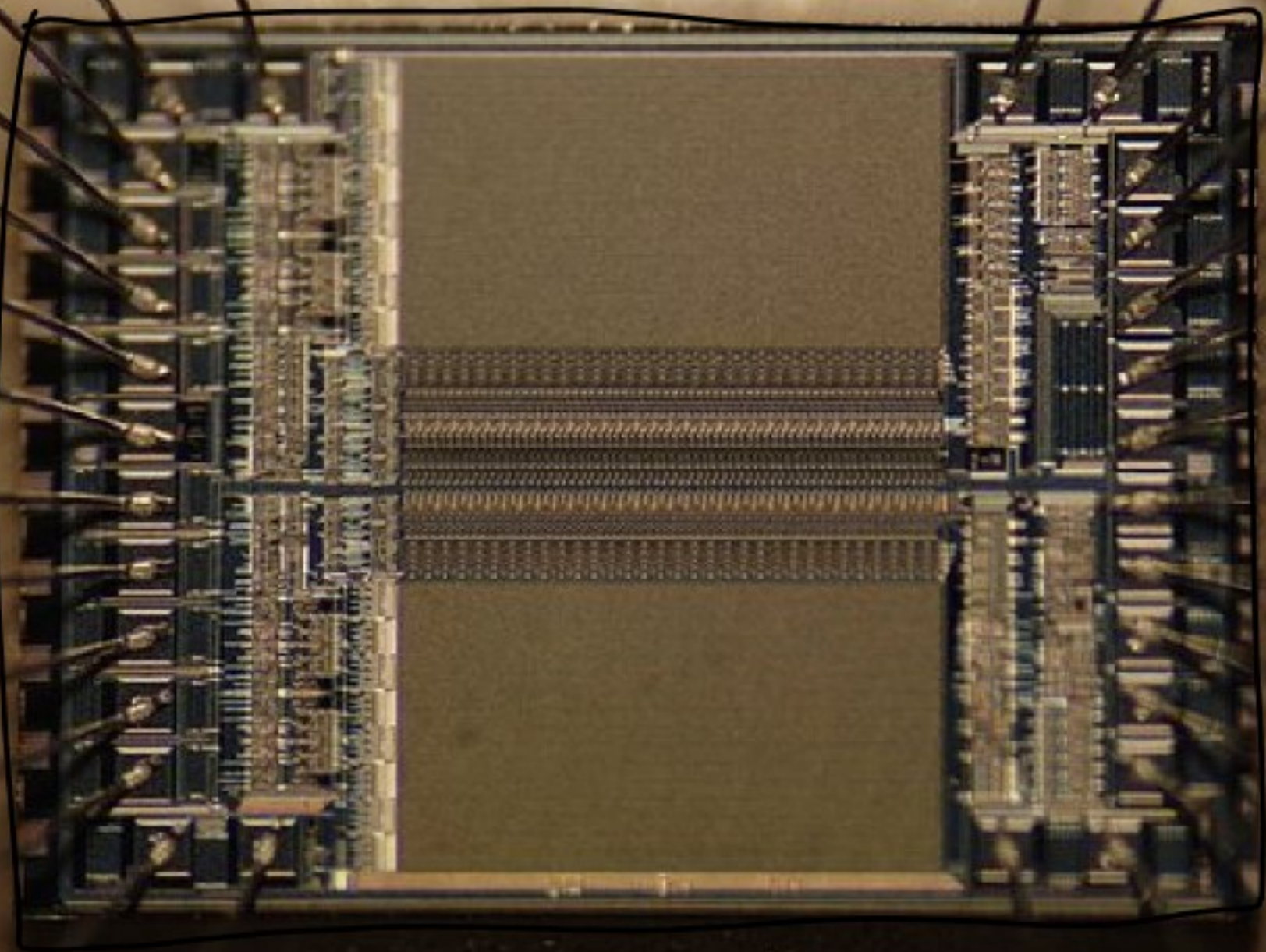
f. Etch exposed oxide

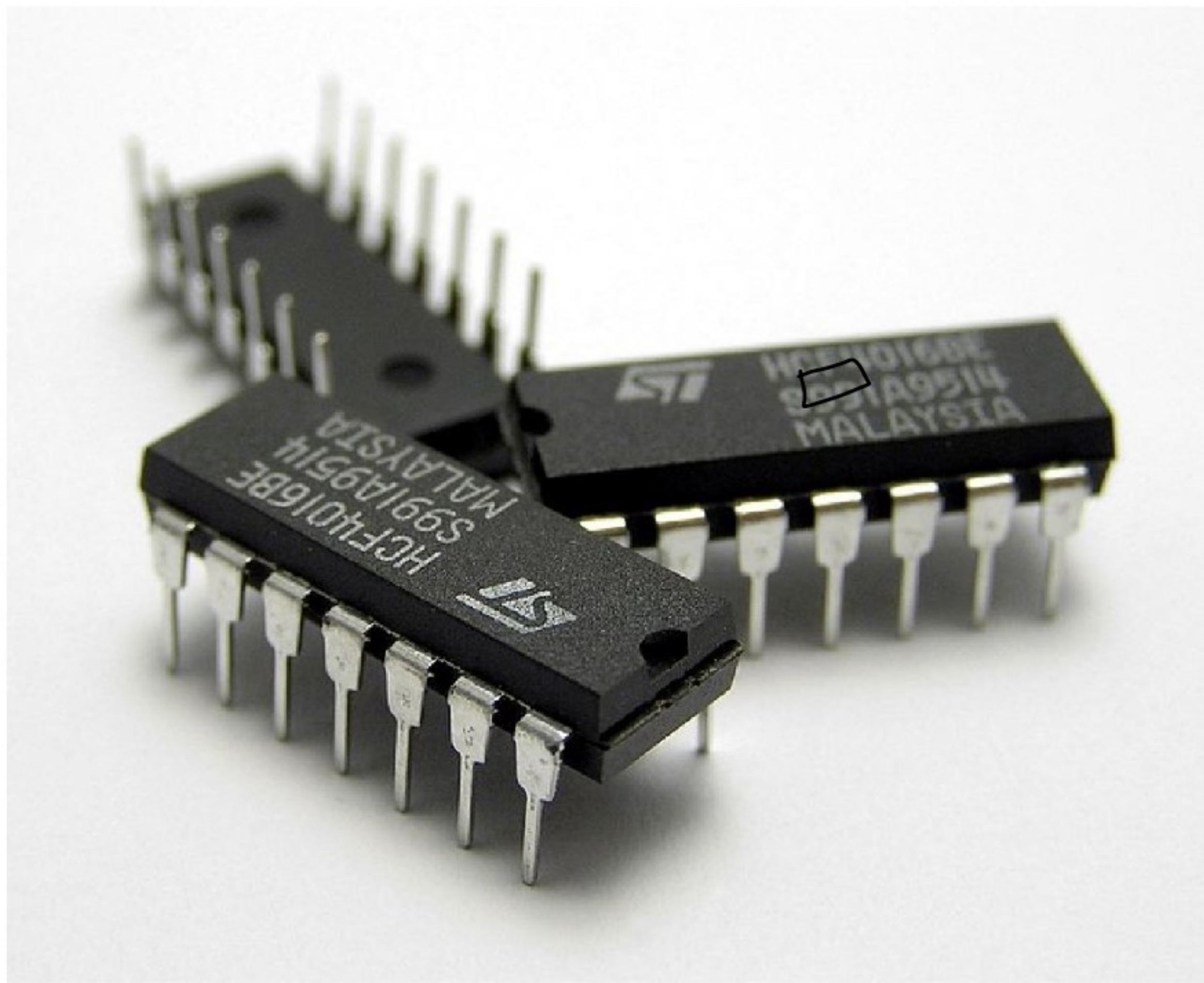


g. Remove remaining photoresist



Die





- ▶ PCB Manufacturing (<https://youtu.be/ljOoGyCso8s>)
- ▶ Chip Fab (<https://youtu.be/2ehSCWoaOqQ>)